

TANK-870e-H110

- High-Performance 6th/7th Generation Intel® Core™ Processor
- Fanless Embedded Computer

Features

- 6th/7th Gen Intel® Core™ processor platform with Intel® H110 chipset and DDR4 memory
- Support dual display VGA+HDMI™
- On-board internal power connector for providing power to add-on cards
- Great flexibility for hardware expansion



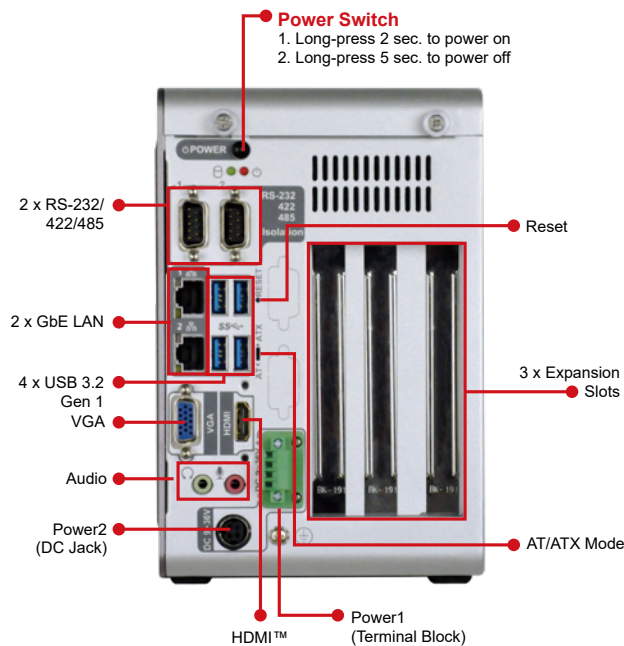
Specifications

Model Name		TANK-870e-H110
Chassis	Color	Dark silver purple + Silver
	Dimensions (WxDxH) (mm)	132.6 x 255.2 x 190
	System Fan	Fanless
	Chassis Construction	Extruded aluminum alloys
Motherboard	CPU	7 th Gen Intel® Core™ CPU & Intel® Core™ i5-6500TE 2.3 GHz (up to 3.3 GHz, quad-core, TDP 35)
	Chipset	Intel® H110
	System Memory	2 x SO-DIMM DDR4 2133 (4GB pre-installed)(up to 32GB)
Storage	Hard Drive	2 x 2.5" SATA 6Gb/s HDD/SSD bay
I/O Interfaces	USB	4 x USB 3.2 Gen 1
	Ethernet	2 x RJ-45: 2 x GbE by RTL8119I
	COM Port	2 x RS-232/422/485 with AFC (DB-9 with 2.5kV isolation)
	Display	1 x VGA (up to 1920 x 1200@60Hz) 1 x HDMI™ (up to 3840 x 2160@30Hz)
	Audio	1 x Line-out, 1 x Mic-in
	Wireless	1 x 802.11a/b/g/n/ac (optional)
Expansions	PCIe Mini	1 x Full-size (PCIe/ USB 2.0) 1 x Full-size (PCIe/ USB 2.0/ SATA)
	Backplane	3A: 1 x PCIe x16, 2 x PCI 3B: 1 x PCIe x16, 1 x PCIe x4, 1 x PCI
Power	Power Input	DC Jack: 9 ~ 36V DC Terminal Block: 9 ~ 36V DC
	Power Consumption	19 V@3.44 A (Intel® Core™ i7-6700TE with 8 GB memory)
	Internal Power Connector	5V@3A or 12V@3A
Reliability	Mounting	Wall mount & DIN Rail
	Operating Temperature	i5-6500TE -20°C ~ 60°C with air flow (SSD), 10% ~ 95% non-condensing
	Storage Temperature	-40°C ~ 85°C with air flow (SSD), 5% ~ 90% non-condensing
	Operating Shock	Half-sine wave shock 5G, 11ms, 100 shocks per axis (SSD)
	Operating Vibration	MIL-STD-810G 514.6C-1 (SSD)
	Weight (Net/Gross)	4.2 kg/6.3 kg
	Safety/EMC	CE/FCC/KC
OS	Supported OS	Microsoft® Windows® 8 Embedded, Microsoft® Windows® Embedded Standard 7 E, Microsoft® Windows® 10 IoT Enterprise

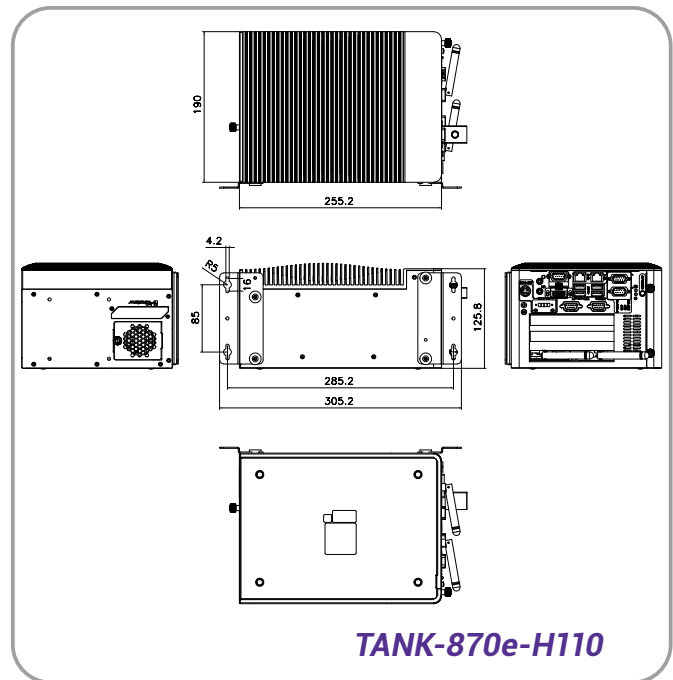
Versatile Expansion Interface

Backplane	3A HPE-3S6		3B HPE-3S7		
Slot	2 x PCI	1 x PCIe x16	1 x PCI	1 x PCIe x4	1 x PCIe x16
Signal	PCI	PCIe x16	PCI	PCIe x1	PCIe x16

Fully Integrated I/O



Dimensions (Unit: mm)



Ordering Information

Part No.	Description
TANK-870e-H110-i5/4G/3A-R12	Ruggedized Fanless embedded system with Intel® Core i5-6500TE 2.3GHz, (up to 3.3 GHz, 4-Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 2 x PCI expansion, VGA/HDMI, 9~36V DC, Powder paint, RoHS
TANK-870e-H110-i5/4G/3B-R12	Ruggedized Fanless embedded system with Intel® Core i5-6500TE 2.3GHz, (up to 3.3 GHz, 4-Core, TDP 35W), 4GB DDR4 pre-installed memory, 1 x PCIe by 16 & 1 x PCIe by 1 & 1 x PCI expansion, VGA/HDMI, 9~36V DC, Powder paint, RoHS

Options

Part No.	Description
32000-000002-RS	European power cord
63040-010120-300-RS	Adapter Power;FSP;FSP120-AHAN3;9NA1206708;Active PFC;Vin:90 ~ 264VAC;120W;Dim:75.6*151.3*25.4mm;Plug=6.5mm;Cable=1500mm;Erp(NO LOAD 0.15W);Vout:12VDC;Din 4Pin/lock;CCL;RoHS
EMB-WIFI-KIT11-R20	1T1R wifi module kit for embedded system, IEEE802.11a/b/g/n/ac WiFi with Bluetooth 4.0/3.0+HS, 1 x wifi module, 2 x 400mm RF cable, 2 x Antenna, RoHS
DK-75-R10	DIN mount kit adapter for VESA-75
TANK-870e-H110-W10E64-V-R10	OS Image with Windows® Embedded Standard 10 E Value 64-bit for TANK-870e-H110-i5 Series, with DVD-ROM, RoHS

Packing List

1 x Chassis Screw

1 x Mounting Bracket